



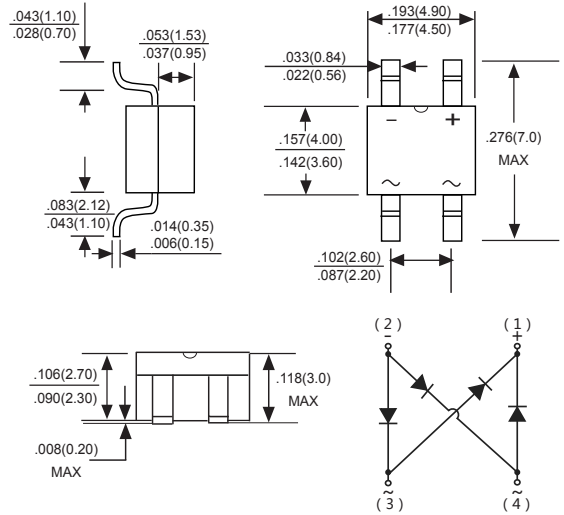
# MB34S THRU MB320S

Voltage Range - 40 to 200 V olts Current - 2.0 Ampere

## Schottky Surface Mount Flat Bridge Rectifier

### Features

- ◆ Reverse Voltage - 40 to 200 V
- ◆ Forward Current - 3.0 A
- ◆ High Surge Current Capability
- ◆ Designed for Surface Mount Application



Dimensions in inches and (millimeters)

### Mechanical Data

**Case :** JEDEC MBS Molded plastic body  
**Terminals :** Solder plated, solderable per MIL-STD-750, Method 2026  
**Polarity :** Polarity symbol marking on body  
**Mounting Position :** Any  
**Weight :** 0.008 ounce, 0.22 grams

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	MDD	MDD	MDD	MDD	MDD	UNITS	
		MB34S	MB36S	MB38S	MB310S	MB320S		
Marking Code								
Maximum repetitive peak reverse voltage	$V_{RRM}$	40	60	80	100	200	V	
Maximum RMS voltage	$V_{RMS}$	28	42	56	70	140	V	
Maximum DC blocking voltage	$V_{DC}$	40	60	80	100	200	V	
Maximum average forward rectified current	$I_{F(AV)}$	3.0						A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	50		70				A
Maximum instantaneous forward voltage at 2A	$V_F$	0.55	0.70	0.85		0.95	V	
Maximum DC reverse current $T_A=25^\circ C$ at rated DC blocking voltage $T_A=100^\circ C$	$I_R$	0.5 10	0.3 5					mA
Typical junction capacitance at 4.0V, 1.0MHz	$C_j$	250	160					pF
Typical thermal resistance	$R_{\theta JA}$	65						°C/W
Operating temperature range	$T_J$	- 5 5 t o + 1 2 5						°C
storage temperature range	$T_{STG}$	-55 to +150						°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.  
 2. Mounted on glass epoxy PC board with 4×1.5"×1.5" ( 3.81×3.81 cm ) copper pad.

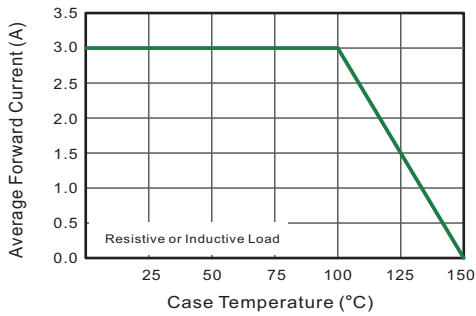


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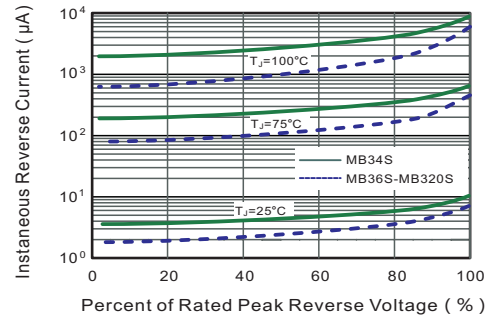
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## Ratings And Characteristic Curves

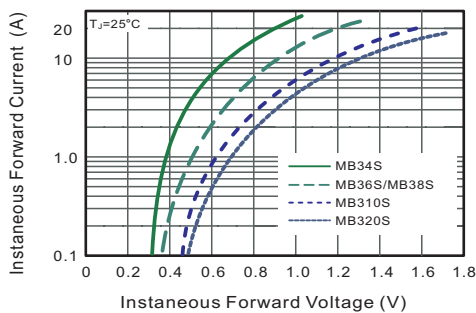
**Fig.1 Forward Current Derating Curve**



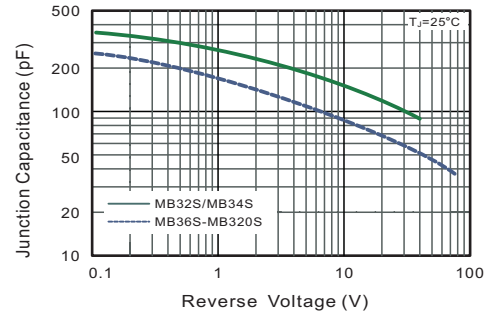
**Fig.2 Typical Reverse Characteristics**



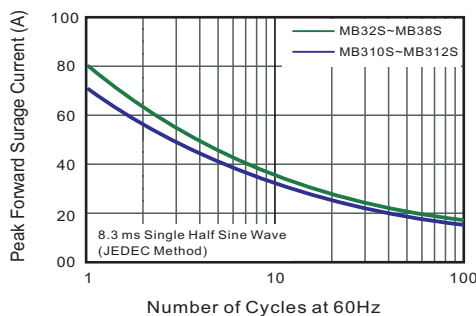
**Fig.3 Typical Forward Characteristic**



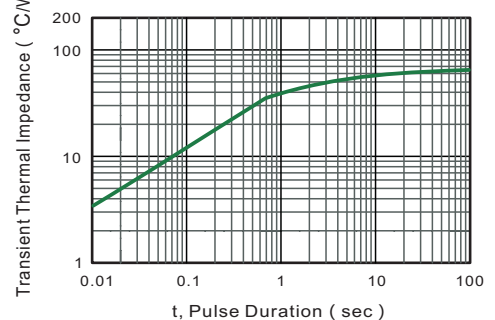
**Fig.4 Typical Junction Capacitance**



**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**

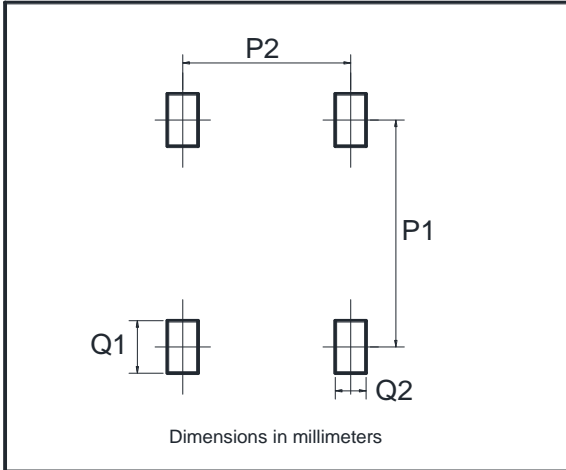


**Fig.6- Typical Transient Thermal Impedance**



The curve above is for reference only.

## Suggested Pad Layout



Dim	Min
P1	6.00
P2	2.40
Q1	1.84
Q2	1.20